

Switching Diodes

Features

- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case: SOD-123FL
- Polarity: Color band denotes cathode end
- Approx. Weight: 0.015g

Ordering Information

Part Number	Marking	Shipping	Reel
1N4148WL-TR3	W1	3000PCS Tape&Reel	7 inchs
1N4148WL-TR12	W1	12000PCS Tape&Reel	13 inchs

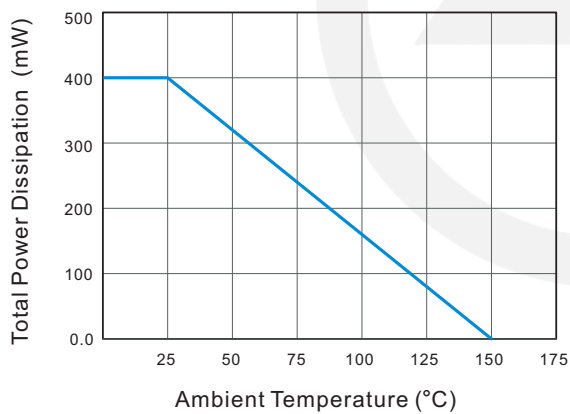
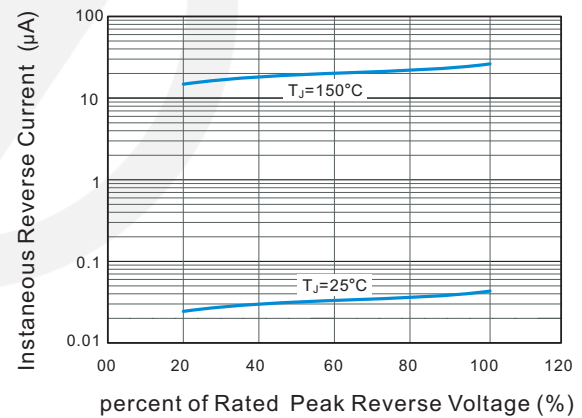
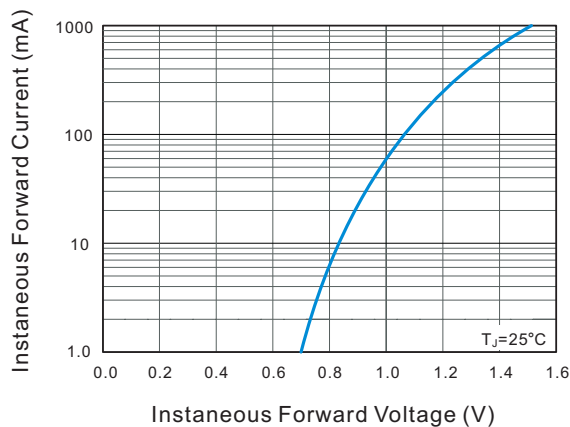
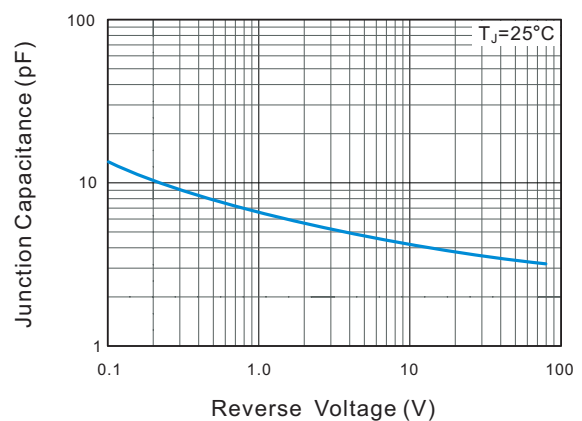
Absolute Maximum Ratings at 25°C

Parameter	Symbol	1N4148WL	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Continuous Forward Current	I_F	300	mA
Non-reptitive Peak Forward Surge Current at 1ms	I_{FSM}	4	A
Total Power Dissipation	P_{tot}	400	mW
Typical Thermal Resistance (Note1)	$R_{\theta JA}$	450	°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Note: (1) PCB mounted with 2.0" X 2.0" (5cm X 5cm) copper pad areas.

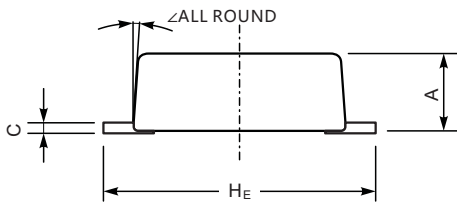
Characteristics at T_a= 25°C

Parameter	Symbol	1N4148WL	Unit
Reverse Breakdown Voltage at I _R =1μA	V _{(BR)R}	75	V
Maximum Forward Voltage at 1mA at 10mA at 50mA at 150mA at 300mA	V _F	0.715 0.855 1.00 1.25 1.5	V
Peak Reverse Current at V _R =20V T _J =25°C at V _R =75V T _J =25°C at V _R =25V T _J =150°C at V _R =75V T _J =150°C	I _R	0.025 1 30 50	μA
Typical Junction Capacitance f=1MHz, V _R =4V	C _j	5	pF
Maximum Reverse Recovery Time	t _{rr} Typical	8	ns

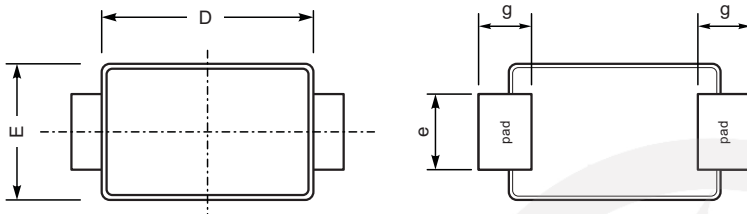
Characteristics Curve
Fig.1 Power Derating Curve

Fig.2 Typical Reverse Characteristics

Fig.3 Typical Instantaneous Forward Characteristics

Fig.4 Typical Junction Capacitance


SOD-123FL Package Outline

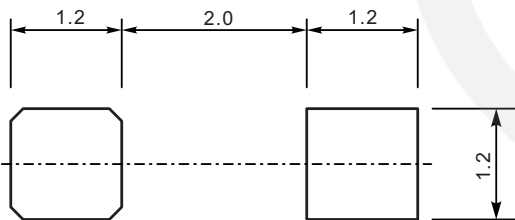
Unit : mm



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.9	1.35
C	0.12	0.20
D	2.6	2.9
E	1.75	1.95
e	0.8	1.1
g	0.7	0.9
H _E	3.5	3.8
∠	7°	



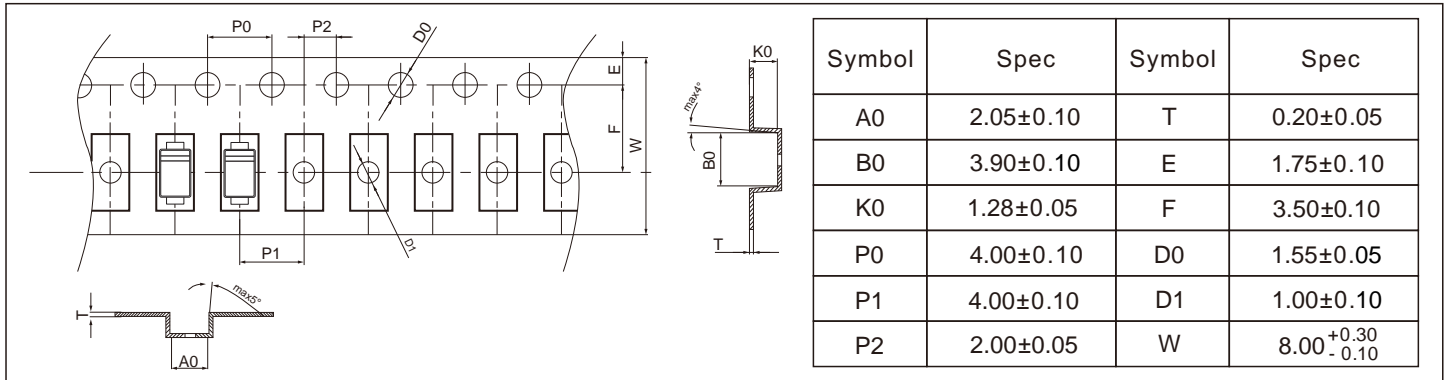
SOD-123FL Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$
 3. The pad layout is for reference purpose only.

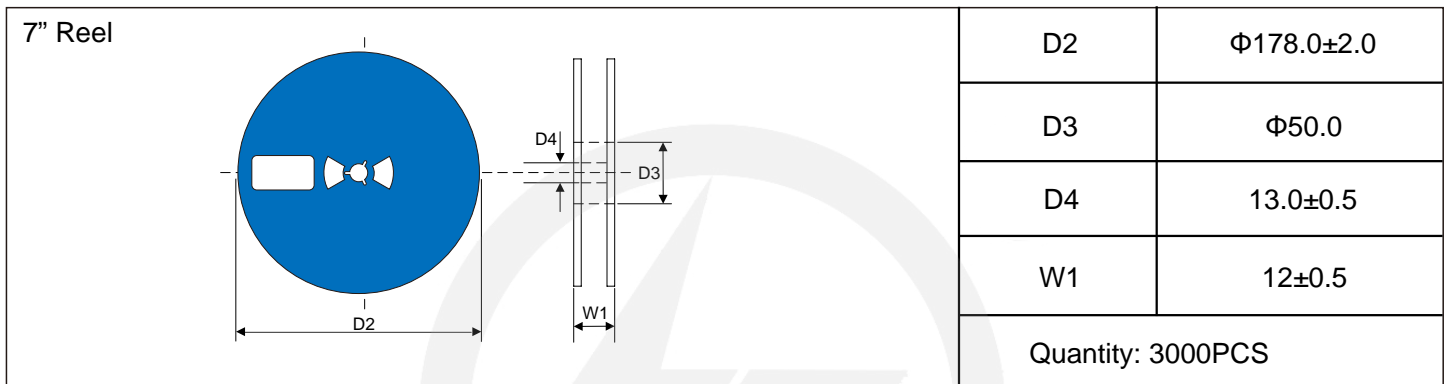
Carrier Tape Dimensions

Unit : mm



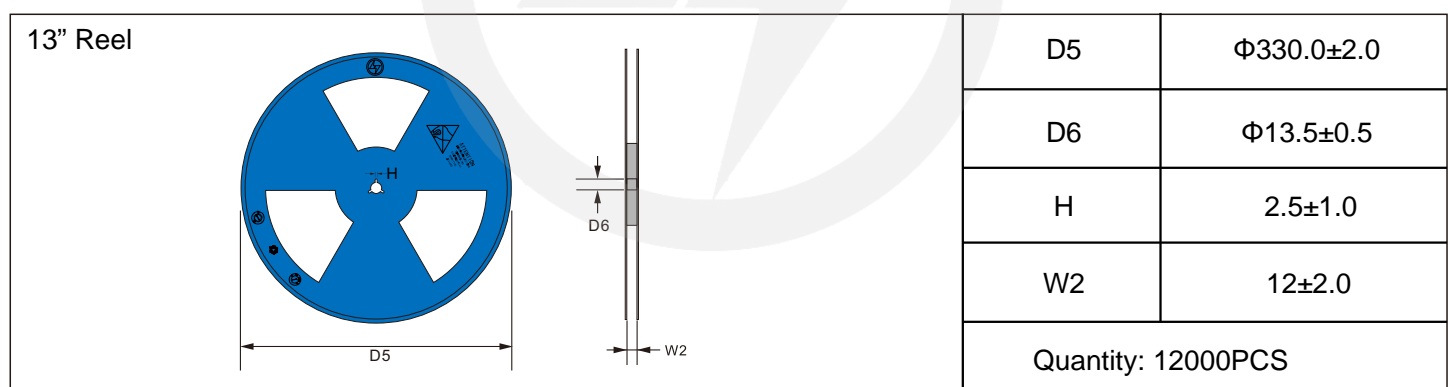
Reel Dimensions

Unit : mm

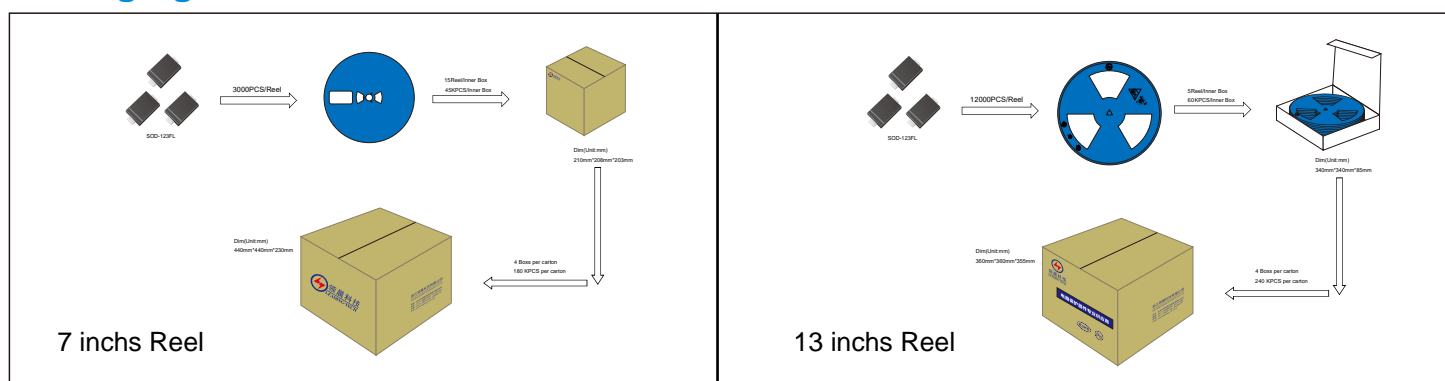


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision Content	Revision Reason	Revision Person	Note
01	2024.04.19	2024.04.19	3.0	New file	/	Ding	